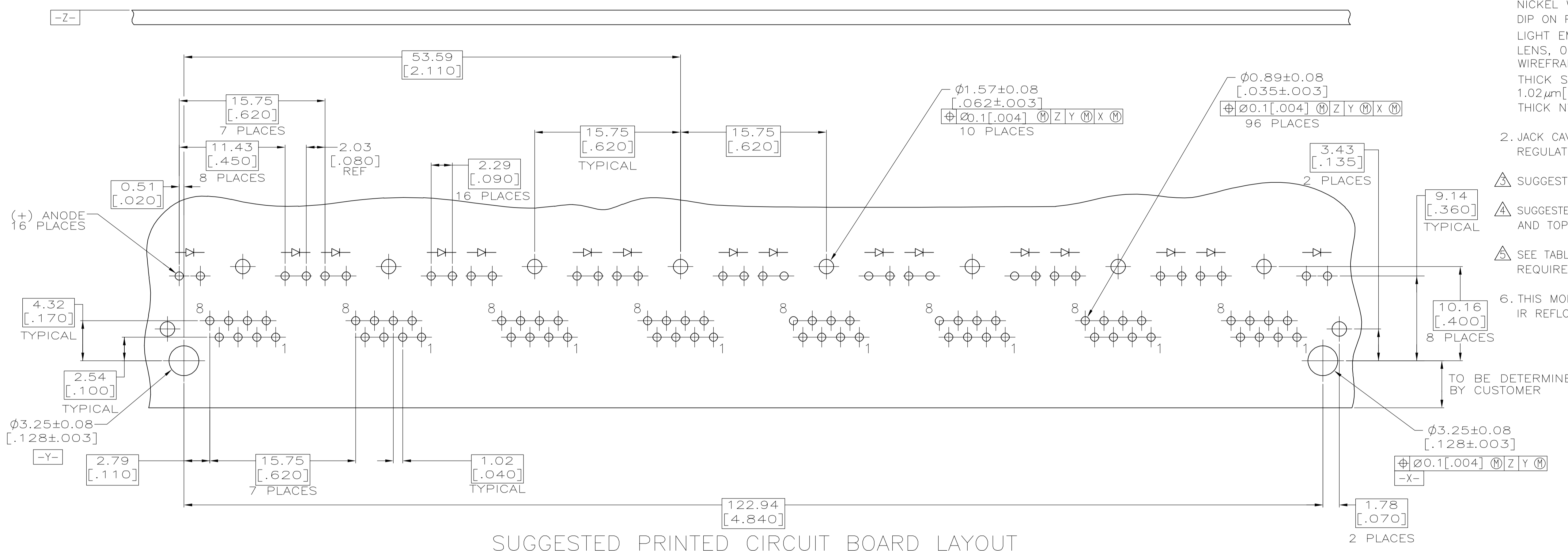
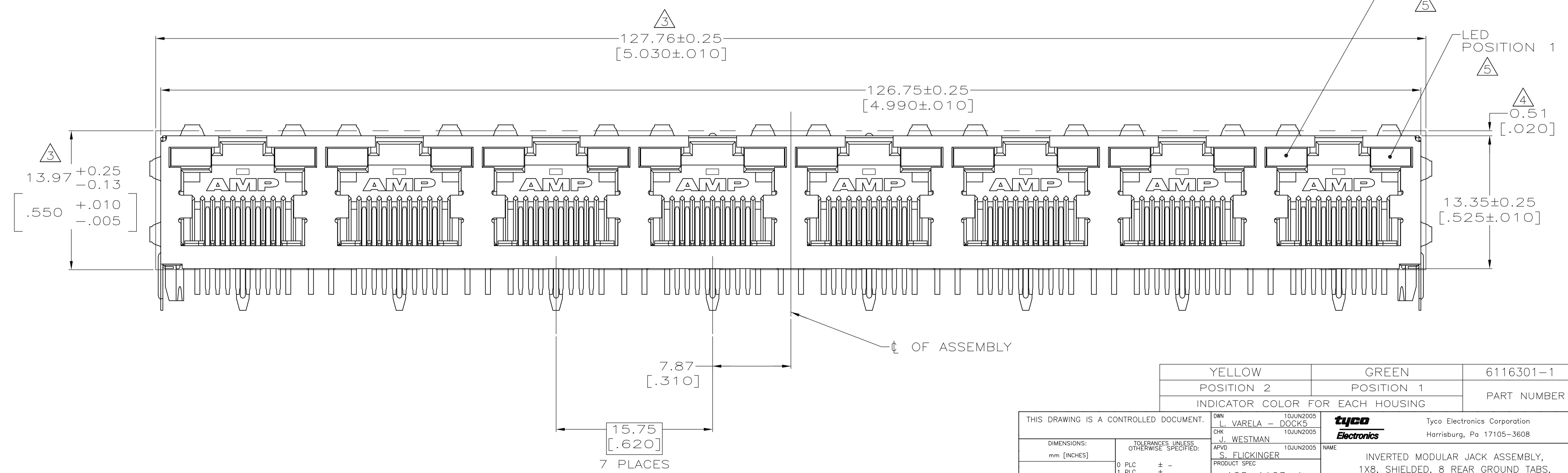
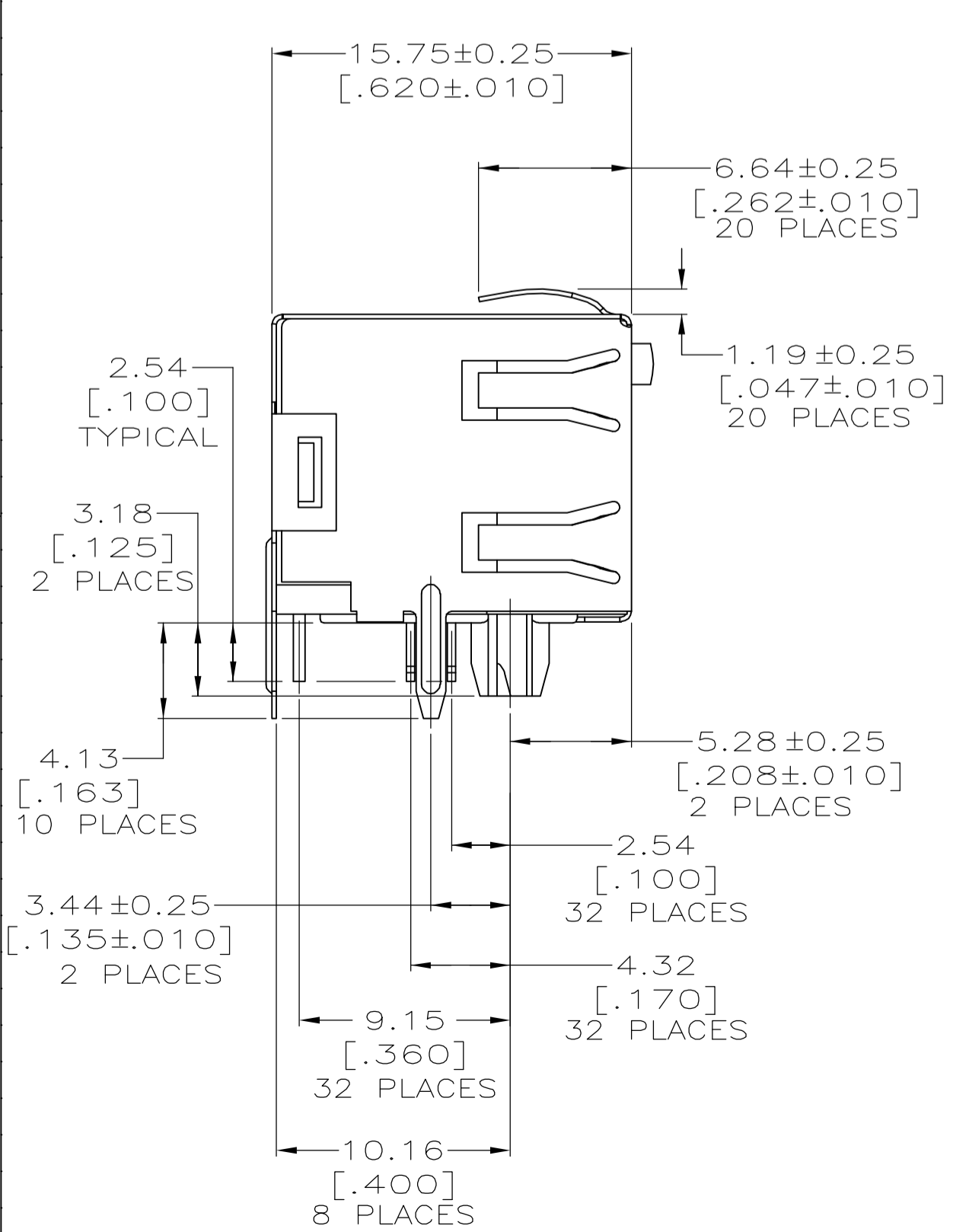


REVISONS		DATE	BY	APP'D
AA	22	10JUN2005	LV	SF
A	REV PER EC	0511-0201-04		

- MATERIAL:**
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27μm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27μm[.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27μm[.000050] MINIMUM SATIN NICKEL WITH 2.03μm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μm[.0003500] THICK Sn/Cu OVER 2.03 μm[.000080] THICK Ag OVER 1.02μm[.000040] THICK Cu OVER 3.56 μm[.000140] THICK Ni OVER 1.02μm[.000040] Cu UNDERPLATE
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
3. SUGGESTED PANEL OPENING DIMENSIONS.
4. SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
5. SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



YELLOW	GREEN	6116301-1
POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR FOR EACH HOUSING		
THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONS: mm (INCHES) TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± 0.25(.01) 3 PLC ± 0.13(.005) 4 PLC ± - ANGLES ± - MATERIAL FINISH		
CUSTOMER DRAWING SCALE 1:1 SHEET 1 of 1 REV A		